

DESCRIPTION

SiC Schottky Diode has no switching loss, provides improved system efficiency against Si diodes by utilizing new semiconductor material-Silicon Carbide, enables higher operating frequency, and helps increasing power density and reduction of system size /cost. Its high reliability ensures robust operation during surge or over_voltage conditions.

FEATURES

- Max Junction Temperature 175° C
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery

MECHANICAL DATA

- Case: JEDEC TO-220AC/ITO-220AC/TO-263/TO-252
- Molding compound meets UL94V-0 flammability rating
- Terminals: Lead solderable per J-STD-002 and JESD22-B102
- Polarity: As marked
- Mounting Torque: 10 in-lbs maximum

TYPICAL APPLICATIONS

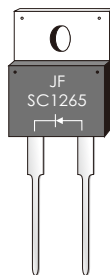
- General Purpose
- SMPS, Solar inverter, UPS
- Power Switching Circuits

KEY PERFORMANCE AND PACKAGE PARAMETERS

Type	V _{DC}	I _F	Q _c	T _{J,max}	Package
SC1265	650V	12A	25nC	175°C	TO-220AC
SC1265F	650V	12A	25nC	175°C	ITO-220AC
SC1265D2	650V	12A	25nC	175°C	TO-263
SC1265M2	650V	12A	25nC	175°C	TO-252

TO-220AC

SC1265



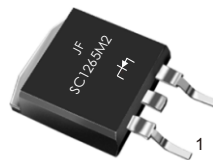
ITO-220AC

SC1265F



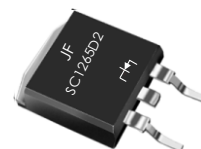
TO-252

SC1265M2



TO-263

SC1265D2



RATINGS AND CHARACTERISTIC OF SC1265XX

MAXIMUM RATINGS

(Ratings at 25° C ambient temperature unless otherwise specified)

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	650	V
Continuous Forward Current for $R_{th(j-c)}$	I_F	12 ($T_c \leq 150^\circ\text{C}$ TO-220/TO-263) 12 ($T_c \leq 128^\circ\text{C}$ TO-252/ITO-220)	A
Non-Repetitive Forward Surge Current (Half-Sine Pulse, $t_p=8.3\text{ms}$)	I_{FSM}	85(25°C) 75(150°C)	A
I^2t value	$\int i^2t$	30 (25°C) 23 (150°C)	A^2S
Diode dv/dt ruggedness($V_R=0\dots650\text{V}$)	dv/dt	80	V/nS
Power dissipation for $R_{th(j-c,max)}$ ($T_c=25^\circ\text{C}$)	P_{tot}	125(TO-220/TO-263) 60(TO-252/ITO-220)	W
Operating junction temperature range	T_j	-55...175	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55...175	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Parameter	Symbol	ITO-220AC	TO-220AC	TO-263	TO-252	Unit
Diode thermal resistance junction-case	$R_{th(j-c)}$	2.5	1.2	1.2	2.5	K/W

RATINGS AND CHARACTERISTIC OF SC1265XX

ELECTRICAL CHARACTERISTICS (T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
DC blocking voltage	V _{DC}	T _j =25...175°C	650			V
Diode forward voltage	V _F	IF=12A Tj=25°C IF=12A Tj=125°C IF=12A Tj=175°C		1.48 1.60 1.85	1.8 1.9 2.1	V
Reverse current	I _R	VR=650V Tj=25°C VR=650V Tj=125°C VR=650V Tj=175°C			20 100 200	uA

DYNAMIC CHARACTERISTICS(at T_j=25°C, unless otherwise specified)

Parameter	Symbol	conditions	Value			Unit
			min	typ	max	
Total capacitive charge	Q _c	VR=650V, IF=12A di/dt=200A/uS Tj=25°C		25		nC
Total capacitance	C _j	V _R =0V, f=1MHz V _R =200V, f=1MHz V _R =400V, f=1MHz Tj=25°C		440 57 46		pF

RATINGS AND CHARACTERISTIC OF SC1265XX

FIG.1-FORWARD CURRENT DERATING CURVE

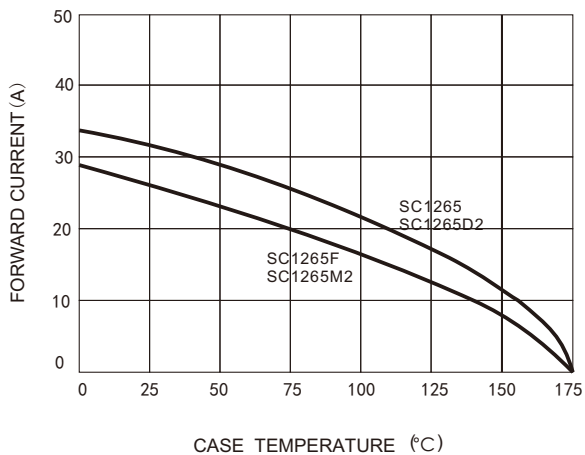


FIG.2-TYPICAL JUNCTION CAPACITANCE

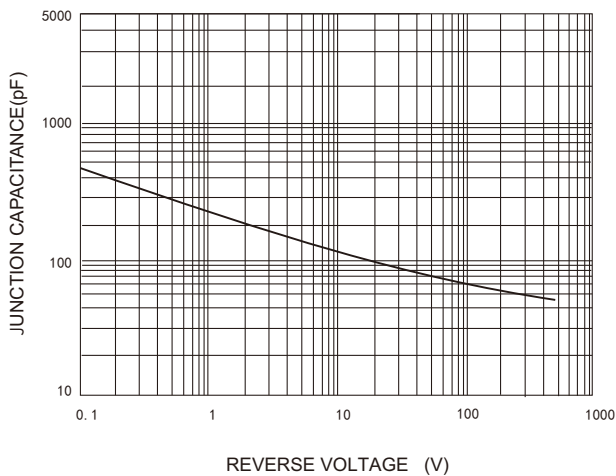


FIG.3-FORWARD CHARACTERISTICS

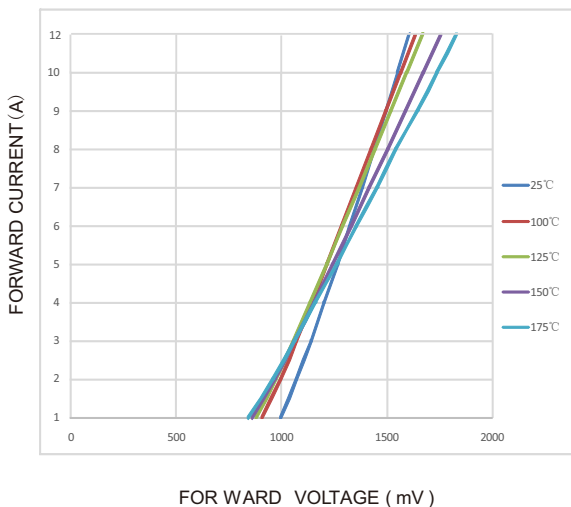
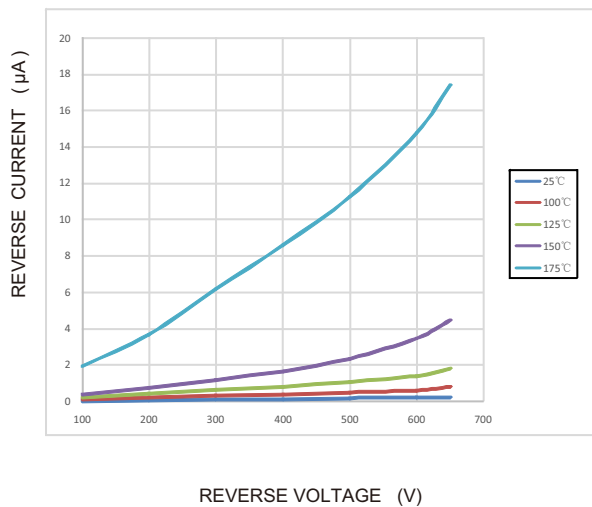
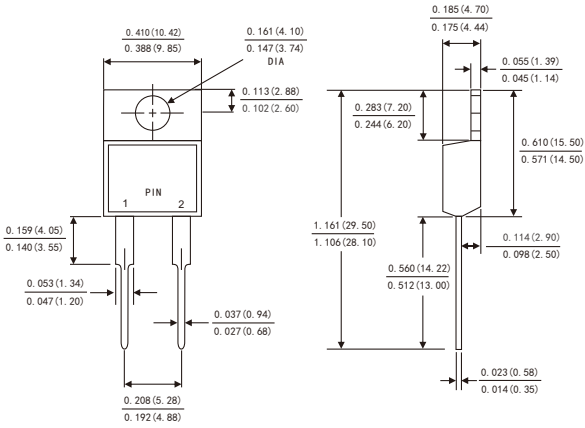


FIG.4-REVERSE CHARACTERISTICS



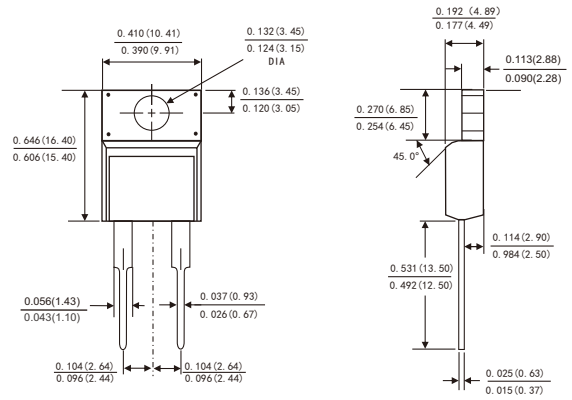
PACKAGE OUTLINE DIMENSIONS

TO-220AC



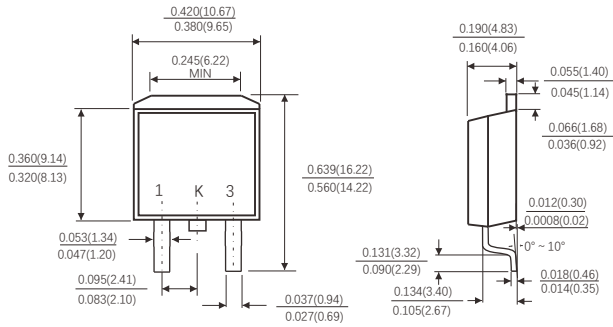
Dimensions in inches and (millimeters)

ITO-220AC

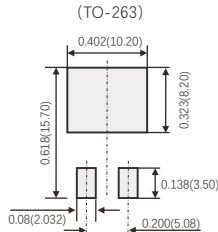


Dimensions in inches and (millimeters)

TO-263

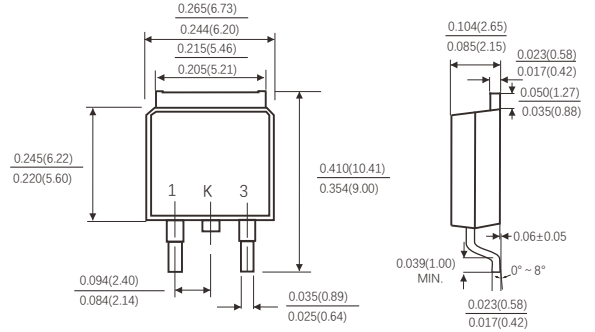


Suggested Pad Layout

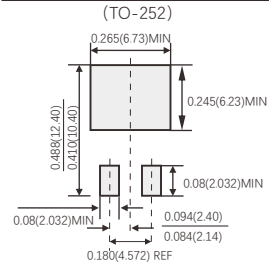


(设计者可参考推荐值根据焊接工艺要求自行确定适合的焊盘尺寸)
(Designers can refer to the recommended values according to the manufacturing process requirements to determine the appropriate pad size)

TO-252



Suggested Pad Layout



(设计者可参考推荐值根据焊接工艺要求自行确定适合的焊盘尺寸)
(Designers can refer to the recommended values according to the manufacturing process requirements to determine the appropriate pad size)

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